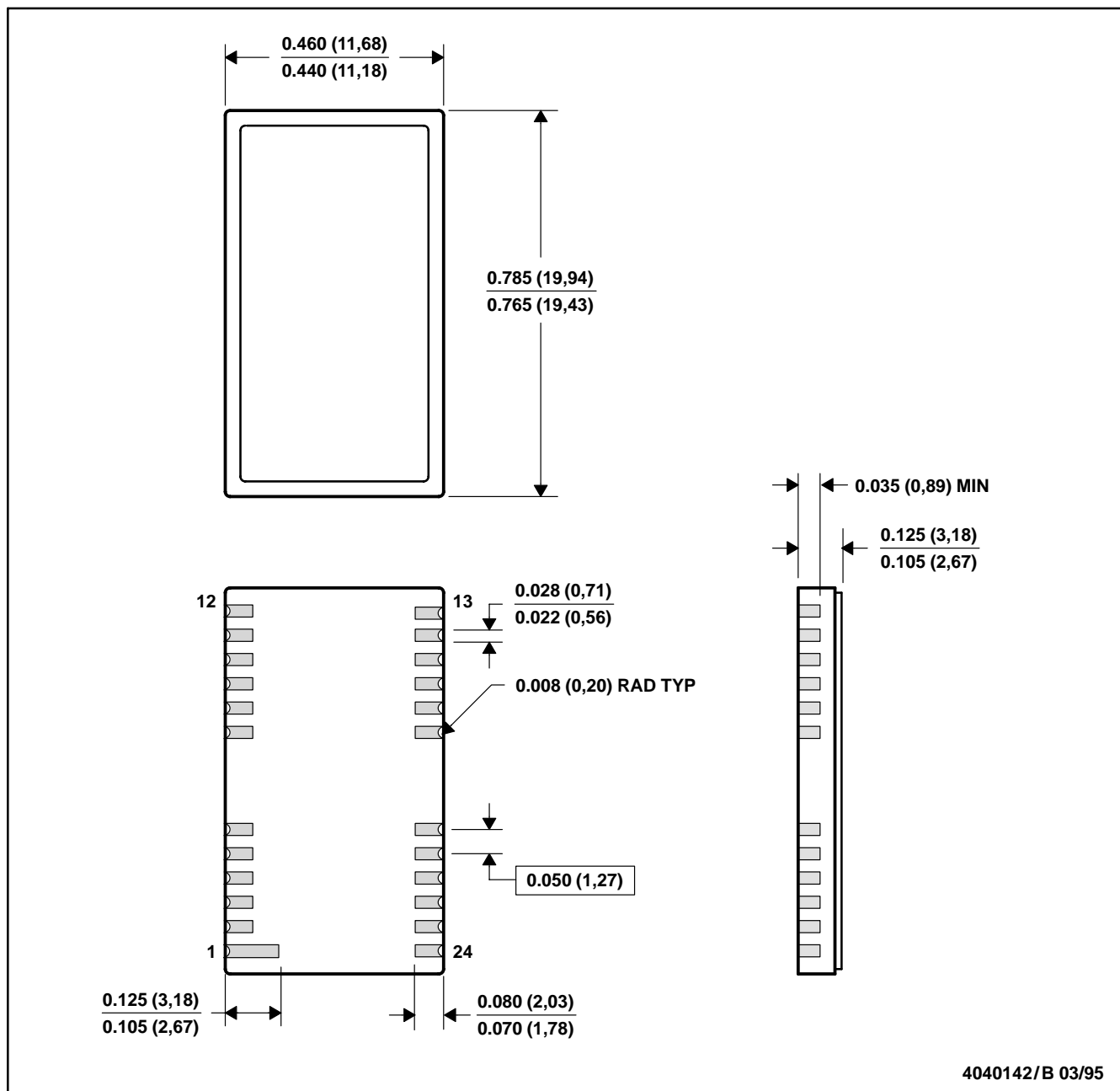


FNC (R-CDCC-N24/28)

LEADLESS CERAMIC CHIP CARRIER



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.

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